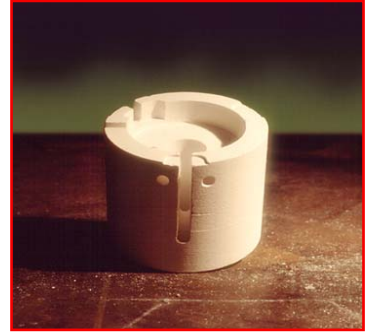


Microporous Silica Ultra Low Thermal Conductivity Boards

Microporous Silica has the lowest thermal conductivity of any rigid board material for service up to 1000°C. Microporous Silica is excellent back-up insulation for high temperature kilns. The very low thermal conductivity of the material makes it possible to reduce the overall thickness of refractory linings and reduce energy consumption. Microporous Silica boards can also be CNC machined to yield intricate shapes, making it an ideal material for thermal analytical equipment insulation.



Properties	Units	GRADE	
		Standard	Super
Service Temperature	°F °C	1800 982	1800 982
Density	lbs/ft ³ (kg/m ³)	18 (300)	18 (300)
Linear Shrinkage 24 hrs @ Temperature 1750°F/954°C	%	-1.3	-1.3
Compressive Resistance @ 10% Compression ASTM C165	lbs/in ²	45	45
Thermal Conductivity ASTM C-177			
500°F (260°C)	BTUin/hrft ² °F (W/mK)	0.193(0.028)	0.145(0.021)
1000°F (538°C)	BTUin/hrft ² °F (W/mK)	0.293(0.042)	0.180(0.026)
1500°F (816°C)	BTUin/hrft ² °F (W/mK)	0.423(0.061)	0.221(0.032)